LATVIAN CHIP
COMPETENCE
CENTRE

LCCC - Issue #2 (Autumn 2025)

Welcome to the second issue of the LCCC Newsletter!

The Latvian Chip Competence Centre (LCCC) continues its mission to strengthen Latvia’s role in the European semiconductor landscape. In line with the EU Chips Act, we are **working to expand national capabilities in microelectronics, support SMEs and startups, and foster talent development** through collaboration, training, and innovation-driven initiatives.

Since the launch of the project, **LCCC has made important progress** – from mapping Latvia’s semiconductor ecosystem to engaging with regional and international partners. This **newsletter highlights recent developments**, including key insights from industry surveys, events, and strategic dialogues that shape our next steps.

Stay updated on milestones, success stories, and how you can contribute to building a more resilient and competitive European chip ecosystem.

Recent events

Baltic + Finnish Chip Competence Centre Workshop

On 2 October, **The Latvian Chip Competence Centre hosted the Baltic + Finnish Chip Competence Centre Workshop** at Riga Technical University to strengthen regional cooperation and align efforts within the European semiconductor ecosystem. **Representatives from Latvia, Lithuania, Estonia, and Finland** exchanged best practices, discussed sustainability models, and explored opportunities for joint research, training, and policy alignment.

Discussions covered four main themes:

- **Operations and Sustainability**: Addressing funding continuity and defining practical collaboration models beyond the Chips JU framework.
- **Outreach and Policy**: Developing joint communication strategies, strengthening policymaker engagement, and improving visibility of the regional chip ecosystem.
- **Common Technology Offers**: Mapping value chains, coordinating research services, and enhancing access to pilot lines for SMEs and startups.

- **Training and Skills Development**: Creating shared education programmes, lifelong learning platforms, and strategies to attract and retain semiconductor talent.

The workshop concluded with an **agreement to deepen cooperation through joint initiatives, shared communication tools, and coordinated training programmes** – laying the foundation for a Memorandum of Understanding to formalize Baltic–Nordic collaboration in the semiconductor field.

LCCC at Techritory 2025: Strengthening Regional Cooperation and Showcasing Latvia s Chip Ecosystem

On 22 October 2025, the Latvian Chip Competence Centre (LCCC) actively contributed to three high-level events at the Techritory Forum in Riga, highlighting Latvia’s growing role in the European semiconductor ecosystem and reinforcing ties across the Baltic and Nordic regions.

The day began with the roundtable **“From the Baltics to the Nordics: Building Alliances for Global Semiconductor Competitiveness”**, which gathered representatives from national chip competence centres to discuss regional collaboration, strategic alignment, and shared challenges. Participants explored how coordinated efforts can support innovation, boost resilience, and accelerate Europe’s chip industry development.

This was followed by a landmark **Signing Ceremony of the Memorandum of Understanding (MoU)** between the Baltic Chip Competence Centres of Latvia, Lithuania, and Estonia. The agreement formalises cooperation and paves the way for joint research, talent development, and infrastructure sharing, thus establishing the Baltic region as an emerging hub for semiconductor excellence.

The final event of the day was the **Latvia’s Chip Ecosystem Meeting**, which brought together national stakeholders to align strategic priorities and review key achievements. Highlights included the presentation of Latvia’s chip ecosystem mapping and the results of the national industry survey, offering a data-driven foundation for future collaboration. Participants engaged in thematic discussions on services, policy, education, and outreach, reinforcing the importance of cross-sector dialogue in driving the ecosystem forward.

Together, these events demonstrated Latvia’s active involvement in shaping Europe’s semiconductor future and its commitment to fostering a competitive and connected regional value chain.

LCCC at SEMICON Europa 2025: Fostering Cross-Border Collaboration for a Resilient Semiconductor Future

Representatives of the Latvian Chip Competence Centre participated in **SEMICON Europa 2025**, held from 18 to 21 November in Munich, Germany. Co-located with Productronica, this year's edition was themed "Global Collaborations for European Economic Resilience" and **brought together leaders from across the semiconductor and microelectronics sectors**. The event emphasised the importance of cross-border cooperation as a strategic pillar for safeguarding Europe's prosperity, sustainability, and technological sovereignty.

Discussions highlighted how innovation and environmental responsibility must advance in tandem to ensure long-term resilience and competitiveness within the global semiconductor value chain.

Upcoming Events

Taiwan–Europe Chip Innovation Forum 2025 (TECIF)

📅 November 27–28, 2025
📍 Dresden, Germany
🔗 More info & registration

Hosted by the National Institutes of Applied Research, imec, Europractice, and TU Dresden, this year's **TECIF focuses on Technology Innovation, Talent Cultivation, and Cross-Regional Collaboration**. With keynote speakers from ESMC and Synopsys, it will spotlight key themes such as **Advanced Packaging, Silicon Photonics, Smart Sensing, and Emerging Memory.**

The forum underscores the role of education and skills in supporting a sustainable semiconductor ecosystem and aims to foster strategic Europe–Taiwan partnerships in chip innovation. TECIF is a key event for aligning international R&I strategies and for showcasing Europe's collaborative potential in global semiconductor development.

EFECS 2025 – European Forum for Electronic Components and Systems

📅 December 3–4, 2025
📍 Hilton Hotel, St Julian's, Malta
🔗 More info & registration

EFECS 2025 is the **annual meeting point for the Chips Joint Undertaking (JU) community** and **brings together over 700 participants from across the electronics and semiconductor value chain**. Organised with support from AENEAS, EPoSS, and INSIDE, the forum is a key platform for:

- Showcasing European innovation in electronic components and systems
- Sharing progress and insights from funded projects
- Strengthening cross-sector collaboration

This year's edition **focuses on accelerating the path from research to market, enhancing Europe's resilience, and promoting strategic autonomy** in a rapidly evolving geopolitical landscape. Attendees will benefit from high-level sessions, project exhibitions, and rich networking opportunities with industry, academia, and policymakers.

Image Sensors Europe 2026

📅 March 17–18, 2026
📍 London, UK
🔗 Event site

This is the 20th edition of the **leading conference for the digital imaging and sensor supply chain**. With over 250 industry representatives expected, it focuses on cutting-edge image sensor technologies, CMOS updates, SWIR, SPAD and depth sensing, and applications across automotive, consumer and scientific markets.

SPIE Photonics Europe 2026

📅 April 12–16, 2026
📍 Strasbourg, France
🔗 Event site

This **major cross-disciplinary event covers photonics, optics, sensors, laser technologies, quantum and imaging systems**. It offers a strategic platform for companies and researchers in microelectronics, advanced packaging and integrated photonics to connect, showcase innovations and explore collaborations.

Call for proposal

The **Chips for Europe** Initiative aims to build advanced technological capabilities and boost innovation across the European Union. Related OPEN and Coming Soon Calls can be found here.

🎙️ *Beyond Chips* Podcast by Chips Joint Undertaking

The Chips Joint Undertaking continues its **official podcast** – *Beyond Chips* – offering monthly insights into Europe's dynamic semiconductor ecosystem.

New episodes are released **every first Wednesday of the month**, featuring leading voices from industry, research, and policy. The podcast explores the strategic, technological, and economic dimensions of Europe's chips landscape.

🎧 **Episodes 1–5** are already available, covering challenges, opportunities, and key innovations that are shaping the future of semiconductors in Europe.

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